Bi-CDMOS LSI

ON Semiconductor®

http://onsemi.com

For Car Audio Systems Multi-Power Supply IC

Overview

The LV56841PVD is a power supply IC suitable for CD receiver system for car audio system.

This IC integrates 5 systems of regulator output, 2 systems of high side power switch, over-current protector, overvoltage protector and over-heat protector .

Supply for SW33V outputs is low voltage specification, which enables drastic reduction of power dissipation compared to the existing model. (the package is HZIP15).

Function

- Low consumption current: 50μA (typ, only V_{DD} output is in operation)
- •5 systems of regulator output

V_{DD} for microcontroller: output voltage: 3.3V, maximum output current: 350mA

Reverse current protection implemented.

For system: output voltage: 3.3V, maximum output current: 350mA

For audio: output voltage: 5 to 12V (set by external resistors), maximum output current: 300mA

For illumination: output voltage: 5 to 12V (set by external resistors), maximum output current: 300mA

For CD: output voltage: 6V, maximum output current: 1500mA

• 2 lines of high side switch with interlock V_{CC}

EXT: Maximum output current: 500mA, voltage difference between input and output: 0.75V

ANT: Maximum output current: 300mA, voltage difference between input and output: 0.5V

• Supply input

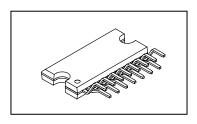
V6IN: 6V for system (SW33V)

V_{CC}1: For internal reference voltage, control circuits, and V_{DD} output.

VCC2: For AUDIO, illumination, CD, EXT/ANT

- Over-current protector
- Overvoltage protector(OVP): V_{CC}1,V_{CC}2 Typ 21V (All outputs except V_{DD} are turned off)
 Overvoltage shutdown(OVS): V6IN Typ 21V (All outputs except V_{DD} are turned off)
- Overheat protector: Typ 175°C
- Pch-LDMOS is used in power output block

(Warning) The protector functions only improve the IC's tolerance and they do not guarantee the safety of the IC if used under the conditions out of safety range or ratings. Use of the IC such as use under over-current protection range, thermal shutdown state or V6IN OVS condition may degrade the IC's reliability and eventually damage the IC.



HZIP15

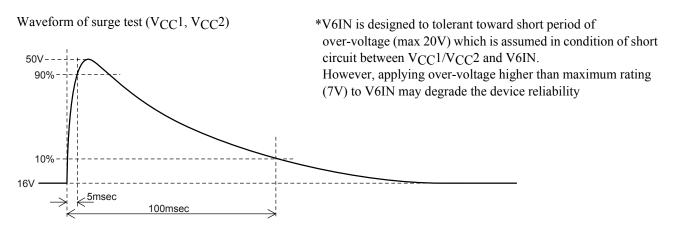
ORDERING INFORMATION

See detailed ordering and shipping information on page 15 of this data sheet.

Absolute Maximum Ratings at Ta = 25°C

Parameter	Symbol	Conditions		Ratings	Unit
Supply voltage	V _{CC} max	V _{CC} 1, V _{CC} 2		36	V
	V6IN max	V6IN (*)		7	V
Input voltage	V _{IN} max	CTRL1, CTRL2		7	V
Allowable power dissipation	Pd max	-Independent IC	Ta ≤ 25°C	1.3	W
		Al heat sink *		5.3	W
		-Size of heatsink: infinite		26	W
Peak supply voltage	V _{CC} peak	See the appendix for wavefo	See the appendix for waveform.		V
Operating ambient temperature	Topr			-40 to +85	°C
Storage temperature	Tstg			-55 to +150	°C
Junction temperature	Tj max			150	°C

^{* :} When the Aluminum heat sink (50mm \times 50mm \times 1.5mm) is used



Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Recommended Operating range at Ta = 25°C

SW33V output

 V_{CC1}

Operating supply voltage 6

. CC-			
Parameter	Conditions	Ratings	Unit
Operating supply voltage 1	V _{DD} output	7 to 16	V
VCC2			
Parameter	Conditions	Ratings	Unit
Operating supply voltage 2	ILM output (10V)	12 to 16	V
	ILM output (8V)	10 to 16	V
Operating supply voltage 3	AUDIO output (9V)	10 to 16	V
	AUDIO output (5V)	8 to 16	٧
Operating supply voltage 4	CD output (I _O = 1.3A)	10.5 to 16	V
	CD output ($I_O \le 1A$)	10 to 16	V
Operating supply voltage 5	EXT output, ANT output	10 to 16	V
V6IN			
Parameter	Conditions	Ratings	Unit
	- 	<u> </u>	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5.5 to 6.5

Electrical Characteristics: $V_{CC}1 = V_{CC}2 = 14.4V$, $V_{CI}N = 6V$ at $T_{CI}N = 25$ °C (*1)

Parameter	Symbol	Symbol Conditions		Ratings		Unit
			min	typ	max	
Quiescent current	Icc	V _{DD} w/out load, CTRL1/2 = "L/L"		50	100	μА
CTRL1 input (ANT/EXT/ILM)	V 1		1 01		0.5	
Low input voltage	V _{IL} 1		0	4.4	0.5	V
M1 input voltage	V _{IM1} 1		0.8	1.1	1.4	V
M2 input voltage	V _{IM2} 1		1.9	2.2	2.5	V
High input voltage	V _{IH} 1		2.9	3.3	5.5	V
Input impedance	R _{IN} 1	input voltage ≤ 3.3V	280	400	480	kΩ
CTRL2 input (CD/AUDIO/SW3	1		1	1		
Low input voltage	V _{IL} 2		0		0.5	V
M1 input voltage	V _{IM1} 2		0.8	1.1	1.4	V
M2 input voltage	V _{IM2} 2		1.9	2.2	2.5	V
High input voltage	V _{IH} 2		2.9	3.3	5.5	V
Input impedance	R _{IN} 2	input voltage ≤ 3.3V	280	400	480	kΩ
V _{DD} output (3.3V) (reverse cu	rrent prevention	diode implemented)	T T	T-		
Output voltage	V _O 1	I _O 1 = 200mA	3.13	3.3	3.47	V
Output current	I ₀ 1	V _O 1 ≥ 3.1V	350			mA
Line regulation	∆V _{OLN} 1	7.5V < V _{CC} 1 < 16V, I _O 1 = 200mA		30	90	mV
Load regulation	∆V _{OLD} 1	1mA < I _O 1 < 200mA		70	150	mV
Dropout voltage1	V _{DROP} 11	I _O 1 = 100mA		2.6	3.1	V
Dropout voltage2	V _{DROP} 12	I _O 1 = 200mA		2.8	3.5	V
Ripple rejection (*2)	R _{REJ} 1	f = 120Hz, V _{CC} 1 = 0.5Vpp I _O 1 = 200mA	40	50		dB
Reverse current	Irev	V _O 1 = 3.3V, V _{CC} 1 = V6IN = 0V		1	50	μΑ
SW33V output (3.3V) ; CTRL2	= "M2 or H"					
Output voltage	V _O 2	I _O 2 = 200mA	3.13	3.3	3.47	V
Output current	I _O 2	$V_O 2 \ge 3.1V$	350			mA
Line regulation	ΔV _{OLN} 2	5.7V < V6IN < 6.5V, I _O 2 = 200mA		30	90	mV
Load regulation	ΔV _{OLD} 2	1mA < I _O 2 < 200mA		70	150	mV
Dropout voltage	V _{DROP} 2	I _O 2 = 200mA		0.25	0.5	V
Ripple rejection (*2)	R _{REJ} 2	$f = 120$ Hz, V6IN or $V_{CC}1 = 0.5$ Vpp $I_{O}2 = 200$ mA	40	50		dB
AUDIO (5-12V)output ; CTRL2	= " H"	-				
AUDIO_F voltage	V _I 3		1.212	1.25	1.288	V
AUDIO_F input current	I _{IN} 3		-1		1	μΑ
AUDIO output voltage 1	V _O 3	$I_{O}3$ = 200mA, R3 = 30kΩ, R4 = 5.6kΩ (*3)	7.65	8.0	8.35	V
AUDIO output voltage 2	V _O 3'	$I_{O}3 = 200$ mA, R3 = 27k Ω , R4 = 4.7k Ω (*3)	8.13	8.5	8.87	V
AUDIO output voltage 3	V _O 3''	$I_{O}3 = 200$ mA, R3 = 24 k Ω , R4 = 3.9 k Ω (*3)	8.6	9.0	9.4	V
AUDIO output voltage 4	V _O 3'''	$I_{O}3 = 200$ mA, R3 = 30 k Ω , R4 = 10 k Ω (*3)	4.75	5.0	5.25	V
AUDIO output current	I _O 3		300			mA
Line regulation	ΔV _{OLN} 3	10V < V _{CC} 2 < 16V, I _O 3 = 200mA		30	90	mV
Load regulation	ΔV _{OLD} 3	1mA < I _O 3 < 200mA		70	150	mV
Dropout voltage 1	V _{DROP} 3	I _O 3 = 200mA		0.4	0.6	V
Ripple rejection (*2)	R _{REJ} 3	f = 120Hz, I _O 3 = 200mA	40	50		dB
ILM (5-12V) output ; CTRL2 =	"M1 or H"	-	l l			
ILM_F voltage	V _I 4		1.212	1.25	1.288	V
ILM_F input current	I _{IN} 4		-1		1	μΑ
ILM output voltage 1	V _O 4	$I_{O}4 = 200$ mA, R1 = 43 k Ω , R2 = 5.1 k Ω (*3)	11.21	11.8	12.39	V
ILM output voltage 2	V _O 4'	$I_{\Omega}4 = 200 \text{mA}, R1 = 56 \text{k}\Omega, R2 = 7.5 \text{k}\Omega \text{ (*3)}$	9.97	10.5	11.03	V
ILM output voltage 3	V _O 4"	$I_{O}4 = 200 \text{mA}, R1 = 30 \text{k}\Omega, R2 = 5.6 \text{k}\Omega \text{ (*3)}$	7.6	8.0	8.4	V
ILM output voltage 4	V _O 4'''	$I_04 = 200$ mA, R1 = 30k Ω , R2 = 10k Ω (*3)	4.75	5.0	5.25	V
	0.	0 ,	1			

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D	0	Conditions		Ratings		11.2
Parameter	Symbol	Conditions	min	typ	max	Unit
Line regulation	∆V _{OLN} 4	$10V < V_{CC}2 < 16V, I_{O}4 = 200$ mA R1 = 30 kΩ, R2 = 5.6 kΩ		30	90	mV
Load regulation	ΔV _{OLD} 4	1mA < I _O 4 < 200mA		70	150	mV
Dropout voltage 1	V _{DROP} 4	I _O 4 = 200mA		0.7	1.05	V
Dropout voltage 2	V _{DROP} 4'	I _O 4 = 100mA		0.35	0.53	V
Ripple rejection (*2)	R _{REJ} 4	f = 120Hz, I _O 4 = 200mA	40	50		dB
CD (6V output) ; CTRL2 = "I	M1 or M2 or H"					
Output voltage	V _O 5	I _O 5 = 1000mA	5.7	6.0	6.3	V
Output current	I _O 5	$V_O 5 \ge 5.6V$	1500			mA
Limit current(*4)	llim5	$V_O 5 \ge 5.5V$	1700			mV
Line regulation	ΔV _{OLN} 5	$10.5V < V_{CC}2 < 16V, I_{O}5 = 1000 \text{mA}$		50	100	mV
Load regulation	ΔV _{OLD} 5	10mA < I _O 5 < 1000mA		100	200	mV
Dropout voltage 1	V _{DROP} 5	I _O 5 = 1000mA		1.0	1.5	V
Dropout voltage 2	V _{DROP} 5'	I _O 5 = 500mA		0.5	0.75	V
Ripple rejection (*2)	R _{REJ} 5	f = 120Hz, I _O 5 = 1000mA	40	50		dB
EXT_HS-SW; CTRL1 = "M1	or M2 or H"					
Output voltage	V _O 6	I _O 6 = 500mA	V _{CC} 2-2.5	V _{CC} 2-0.75		V
Output current	I _O 6	$V_O6 \ge V_{CC}2-2.5$	500			mA
ANT_HS-SW; CTRL1 = "H"	<u> </u>		<u> </u>			
Output voltage	V _O 7	I _O 7 = 300mA	V _{CC} 2-1.0	V _{CC} 2-0.5		V
Output current	I _O 7	V _O 7 ≥ V _{CC} 2-1.0	300			mA

^{*1 :} All the specification is defined based on the tests performed under the conditions where Tj and Ta (= 25°C) are almost equal. These tests were performed with pulse load to minimize the increase of junction temperature (Tj).

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{*2 :} guaranteed by design

^{*3 :} Using resistors of tolerance within 1%.

^{*4 :} When the output current is over "Ilim5", the over-current protector circuit operates. The over-current protector circuit is "fold-back" type, and it limits the output current and voltage when it's operating. The output current should be usually limited below lomax that is "min of lo5".

CTRL logic truth table

CTRL1	ANT	ILM	EXT
Н	ON	ON	ON
M2	ON	OFF	ON
M1	OFF	ON	ON
L	OFF	OFF	OFF

CTRL2	AUDIO	SW33V	CD
Н	ON	ON	ON
M2	OFF	ON	ON
M1	OFF	OFF	ON
L	OFF	OFF	OFF

(Warning) Usage of CTRL pin

When CTRL pin transits between L and M2, since it passes M1, ILM is turned on for a moment. Likewise, when CTRL pin transits between H and M1, since it passes M2, ILM is turned off for a moment.

To avoid operation failure by the above factors, please refer (1) and (2) as shown below for precaution.dd

- Do not connect parasitic capacitor to CTRL as much as possible.
- If use of capacitor for CTRL is required, keep the resistance value as low as possible.
- Make sure that the output load capacitor has enough margin against the voltage fluctuation due to instantaneous ON/OFF.
- (1) The time until a reaction occurs in output after from CTLR ON to OFF (typ)

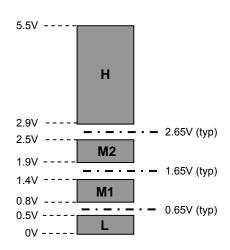
OFF→ON time	27°C
CTRL1→ILM	6.0µsec

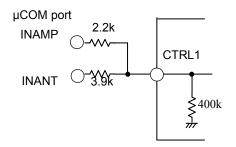
Due to quality fluctuation of ICs in manufacturing process, the above-mentioned time can be shorted by 10 to 20%.

(2)The time until output starts to react shifting from CTRL ON \rightarrow OFF control :

ON→OFF time	27°C
CTRL1→ILM	2.3µsec

CTRL1/2 voltage range and threshold

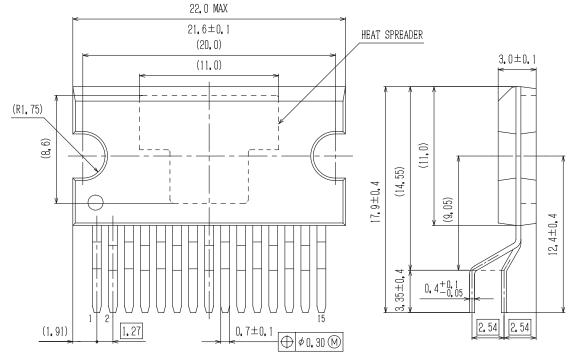




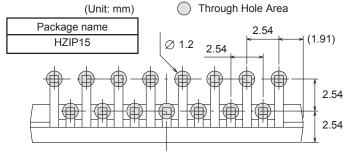
Package Dimensions

unit: mm (typ)

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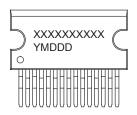


SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

GENERIC MARKING DIAGRAM*

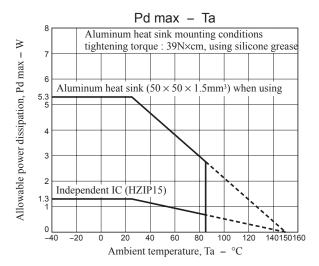


XXXXX = Specific Device Code Y = Year M = Month DDD = Additional Traceability Data

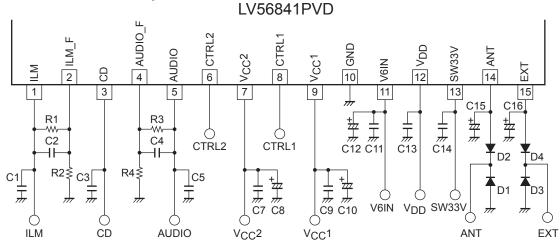
^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present.

• Allowable power dissipation derating curve



Application Circuit Example

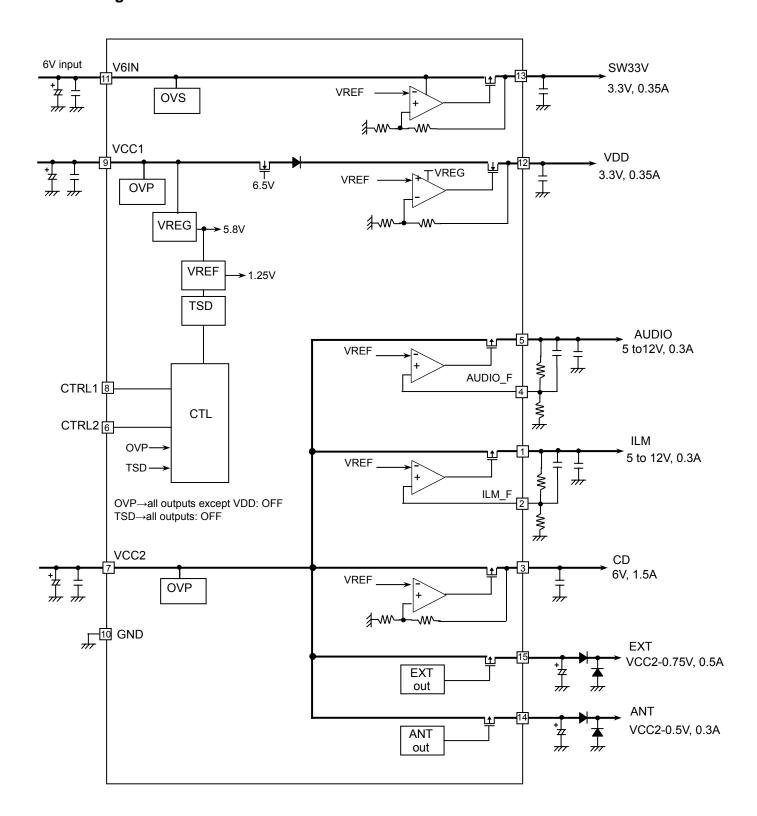


Peripheral parts

Part name	Description	Recommended value	Note
C1, C3, C5, C13, C14	output stabilization capacitor	greater than10μF (*1)	
C2, C4	output stabilization capacitor	0pF	Ceramic capacitor
C8, C10, C12	Capacitor for bypass power supply	C8: greater than 100μF	Make sure to implement close to
		C10,C12: greater than 47μF	V _{CC} and GND.
C7, C9, C11	Capacitor for oscillation protector	greater than 0.22μF	
C15, C16	Capacitor for EXT/ANT output stabilization	greater than 2.2μF	
		R1/R2	Use resistors of tolerance within 1%
		43kΩ/5.1kΩ : V _O = 12V	
R1, R2	ILM voltage setting	$56kΩ/7.5kΩ : V_O = 10.5V$	
		$30k\Omega/5.6k\Omega$: $V_O = 8V$	
		$30k\Omega/10k\Omega : V_O = 5V$	
		R3/R4	Use resistors of tolerance within 1%
		$30k\Omega/10k\Omega$: V _O = 5V	
R3, R4	AUDIO voltage setting	30kΩ/ 5.6 kΩ : V _O = 8.0 V	
		$27kΩ/4.7kΩ : V_O = 8.5V$	
		$24k\Omega/3.9k\Omega$: $V_O = 9V$	
D1, D2, D3, D4	Internal device protector diode	ON Semiconductor	
		SB1003M3	

^(*1) Make sure that output capacitors are greater than 10uF and meets the condition of ESR = 0.001 to 10Ω , in which voltage/ temperature dependence and unit differences are taken into consideration. Moreover, in case of electrolytic capacitor, high-frequency characteristics should be sufficiently good.

Block Diagram



Pin Function

Pin No.	Pin name	Description	Equivalent Circuit
1	ILM	ILM output When CTRL1 = M1, H, ILM is ON	7 Vcc2 Vcc2 Vcc2 Vcc2
2	ILM_F	ILM voltage adjust	$ \begin{array}{c c} \hline 2 & \downarrow \\ \hline 1 & \downarrow \\ \hline 10 & \downarrow \\ \hline GND \end{array} $
3	CD	CD output When CTRL2 = M1, M2, H, CD is ON 6V/1.5A	$\begin{array}{c} 7 \\ \hline \\ 3 \\ \hline \\ 45 \text{k} \Omega \end{array}$
4	AUDIO_F	AUDIO voltage adjust	7 Vcc ² Vcc ² Vcc ²
5	AUDIO	AUDIO output When CTRL2 = H AUDIO is ON	$ \begin{array}{c c} 4 & \downarrow \\ 1 & \downarrow \\ 1 & \downarrow \\ \hline $
6	CTRL2	CTRL2 input 4-value input	$ \begin{array}{c c} \hline 9 & V_{CC1} \\ \hline 6 & W_{85k\Omega} \\ \hline 185k\Omega \\ \hline 75k\Omega \end{array} $
7	V _{CC} 2	Power supply	

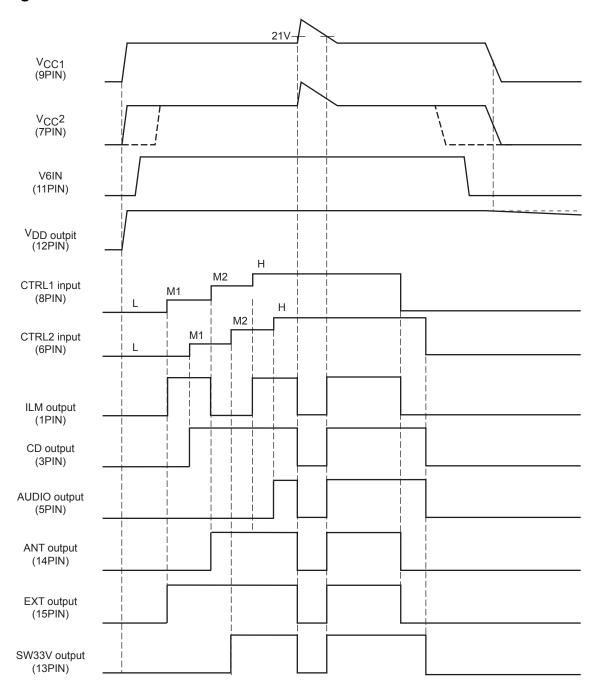
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Continued from preceding page. Pin No. Pin name Description **Equivalent Circuit** CTRL1 8 CTRL1 input V_{CC}1 4-value input $\frac{10k\Omega}{10}$ ₹85kΩ **≱**185kΩ 0.5V **≨**45kΩ 計 ₹ ₹75kΩ GND 9 V_{CC}1 Power supply V_{CC^2} V6IN V_{CC}1 (7)(9) (11) GND 10 GND 太 11 V6IN Power supply (10) GND 12 V_{DD} V_{DD} output V_CC1 3.3V/0.35A (11) \(\frac{\dagger}{\dagger}\) (12) ≸230kΩ 本 ≹2kΩ ≸140kΩ (10) GND 13 SW33V SW33V output (11) -V6IN When CTRL2 = M2, H SW33V is ON 3.3V/0.35A (13) **≨**230kΩ **\$140kΩ \$1kΩ** (10) GND ANT 14 ANT output 7 V_{CC}2 When CTRL1 = M2, H ≸100kΩ ANT is ON V_{CC}-0.5V/300mA (14) (10) GND

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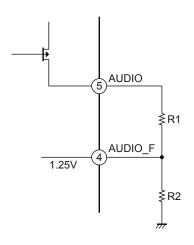
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Pin No.	Pin name	Description	Equivalent Circuit					
15	EXT	EXT output When CTRL1 = M1, M2, H, EXT is ON V _{CC} -0.5V/500mA	7 V _{CC} 2 100kΩ 100kΩ 100kΩ (SND)					
			(10)					

Timing Chart



Caution: The above values are obtained when typ.

• How to set AUDIO output voltage



AUDIO_F is determined by internal band-gap reference voltage (typ = 1.25V).

AUDIO output voltage expression

$$AUDIO = (\frac{R_1}{R_2} + 1) \times 1.25[V]$$

$$\frac{R_1}{R_2} = \frac{AUDIO}{1.25} - 1$$

Set the ratio of R1 and R2 to satisfy above expression.

(ex) AUDIO = 9V setting

$$\frac{R_1}{R_2} = \frac{9}{1.25} - 1 = 6.2$$

$$\frac{R_1}{R_2} = \frac{24k\Omega}{3.9k\Omega} \cong 6.15$$

$$\frac{R_1}{R_2} = \frac{24k\Omega}{3.9k\Omega} \cong 6.15$$

$$AUDIO = (6.15+1) \times 1.25V \cong 8.94V$$

• ILM output voltage is similarly calculated as AUDIO output.

(ex)
$$ILM = 10.5V$$
 setting

$$\frac{R_1}{R_2} = \frac{10.5}{1.25} - 1 = 7.4$$

$$\frac{R_1}{R_2} = \frac{56k\Omega}{7.5k\Omega} \cong 7.46$$

$$ILM = (7.46 + 1) \times 1.25V \cong \boxed{10.575V}$$

Note: The above values are typical values. These values have variation among the range of their tolerances.

HZIP15 Heat sink attachment

Heat sinks are used to lower the semiconductor device junction temperature by leading the head generated by the device to the outer environment and dissipating that heat.

a. Unless otherwise specified, for power ICs with tabs and power ICs with attached heat sinks, solder must not be applied to the heat sink or tabs.

b. Heat sink attachment

- Use flat-head screws to attach heat sinks.
- Use also washer to protect the package.
- Use tightening torques in the ranges 39-59Ncm (4-6kgcm).
- If tapping screws are used, do not use screws with a diameter larger than the holes in the semiconductor device itself.
- Do not make gap, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- Take care a position of via hole.
- Do not allow dirt, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- Verify that there are no press burrs or screw-hole burrs on the heat sink.
- Warping in heat sinks and printed circuit boards must be no more than 0.05 mm between screw holes, for either concave or convex warping.
- Twisting must be limited to under 0.05 mm.
- Heat sink and semiconductor device are mounted in parallel.

 Take care of electric or compressed air drivers
- The speed of these torque wrenches should never exceed 700 rpm, and should typically be about 400 rpm.

Heat sink gap Via hole

mashine screv

c. Silicone grease

- Spread the silicone grease evenly when mounting heat sinks.
- Recommends YG-6260 (Momentive Performance Materials Japan LLC)

d. Mount

- First mount the heat sink on the semiconductor device, and then mount that assembly on the printed circuit board.
- When attaching a heat sink after mounting a semiconductor device into the printed circuit board, when tightening up a heat sink with the screw, the mechanical stress which is impossible to the semiconductor device and the pin doesn't hang.
- e. When mounting the semiconductor device to the heat sink using jigs, etc.,
 - Take care not to allow the device to ride onto the jig or positioning dowel.
 - Design the jig so that no unreasonable mechanical stress is applied to the semiconductor device.

f. Heat sink screw holes

- Be sure that chamfering and shear drop of heat sinks must not be larger than the diameter of screw head used.
- When using nuts, do not make the heat sink hole diameters larger than the diameter of the head of the screws used. A hole diameter about 15% larger than the diameter of the screw is desirable.
- When tap screws are used, be sure that the diameter of the holes in the heat sink are not too small. A diameter about 15% smaller than the diameter of the screw is desirable.
- g. There is a method to mount the semiconductor device to the heat sink by using a spring band. But this method is not recommended because of possible displacement due to fluctuation of the spring force with time or vibration.

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
LV56841PVD-XH	HZIP15 (Pb-Free / Halogen Free)	20 / Fan-Fold

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